

TRS3243 3-V to 5.5-V Multichannel RS-232 Line Driver and Receiver **With ± 15 -kV ESD (HBM) Protection**

1 Features

- Operates with 3-V to 5.5-V V_{CC} supply
- Single-chip and single-supply interface for IBM® PC/AT™ serial port
- RS-232 bus-pin ESD protection of ± 15 kV using human-body model (HBM)
- Meets or exceeds the requirements of TIA/EIA-232-F and ITU V.28 standards
- Three drivers and five receivers
- Operates up to 250 kbps
- Low active current: 300- μ A typical
- Low standby current: 1- μ A typical
- External capacitors: $4 \times 0.1 \mu\text{F}$
- Accepts 5-V logic input with 3.3-V supply
- Always-active noninverting receiver output (ROUT2B)
- Operating temperature
 - TRS3243C: 0°C to 70°C
 - TRS3243I: -40°C to 85°C
- Serial-mouse driveability
- Automatic power-down feature to disable driver outputs when no valid RS-232 signal is sensed

2 Applications

- [Battery-powered systems](#)
- [Tablets](#)
- [Notebooks](#)
- [Laptops](#)
- [Hand-held equipment](#)

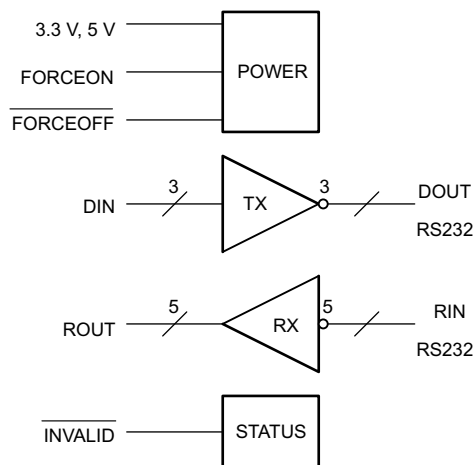
3 Description

The TRS3243 device consists of three line drivers, and five line receivers, which is ideal for DE-9 DTE interface. A ± 15 -kV ESD (HBM) protection pin-to-pin (serial-port connection pins, including GND). Flexible power features save power automatically. Special outputs ROUT2B and $\overline{\text{INVALID}}$ are always enabled to allow checking for ring indicator and valid RS232 input.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
TRS3243	SSOP (28)	10.20 mm \times 5.30 mm
	TSSOP (28)	9.70 mm \times 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (June 2015) to Revision C (October 2022)	Page
• Changed the <i>Thermal Information</i> table.....	5
• Changed the MAX value of I _{CC} Supply current auto-powerdown disabled from 1 mA to 1.2 mA in <i>Electrical Characteristics—Power and Status</i>	5
Changes from Revision A (September 2011) to Revision B (June 2015)	Page
• Added <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> section, <i>Detailed Description</i> , <i>Application and Implementation</i> , <i>Power Supply Recommendations</i> , <i>Layout</i> , <i>Device and Documentation Support</i> and <i>Mechanical, Packaging, and Orderable Information</i> sections.....	1
• Deleted <i>Ordering Information</i> table.....	3

5 Pin Configuration and Functions

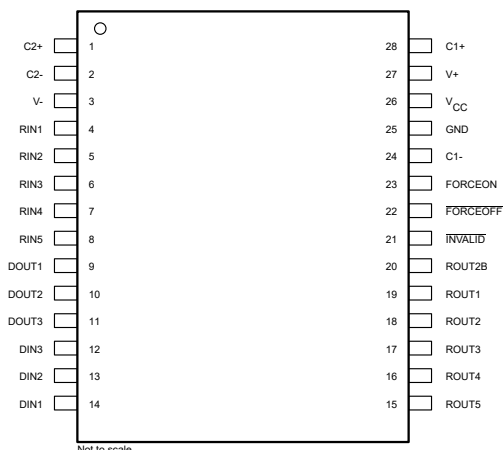


Figure 5-1. DB, PW Packages, 28-Pin SSOP, TSSOP (Top View)

Table 5-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	C2+	—	Positive terminal of the voltage-doubler charge-pump capacitor
2	C2-	—	Negative terminal of the voltage-doubler charge-pump capacitor
3	V-	—	Negative charge pump output voltage
4	RIN1	I	RS-232 receiver inputs
5	RIN2		
6	RIN3		
7	RIN4		
8	RIN5		
9	DOUT1	O	RS-232 driver outputs
10	DOUT2		
11	DOUT3		
12	DIN3	I	Driver inputs
13	DIN2		
14	DIN1		
15	ROUT5	O	Receiver outputs
16	ROUT4		
17	ROUT3		
18	ROUT2		
19	ROUT1		
20	ROUT2B	—	Always-active noninverting receiver output;
21	INVALID	O	Invalid Output Pin
22	FORCEOFF	I	Auto Powerdown Control input (Refer to Truth Table)
23	FORCEON	I	Auto Powerdown Control input (Refer to Truth Table)
24	C1-	—	Negative terminal of the voltage-doubler charge-pump capacitor
25	GND	—	Ground
26	V _{CC}	—	3-V to 5.5-V supply voltage
27	V+	—	Positive charge pump output voltage
28	C1+	—	Positive terminal of the voltage-doubler charge-pump capacitor

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾		−0.3	6	V
V ₊	Positive output supply voltage ⁽²⁾		−0.3	7	V
V _−	Negative output supply voltage ⁽²⁾		0.3	−7	V
V ₊ − V _−	Supply voltage difference ⁽²⁾			13	V
V _I	Input voltage	Driver, FORCEOFF, FORCEON	−0.3	6	V
		Receiver	−25	25	
V _O	Output voltage	Driver	−13.2	13.2	V
		Receiver, INVALID	−0.3	V _{CC} + 0.3	
T _J	Operating virtual junction temperature			150	°C
T _{stg}	Storage temperature		−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 RIN , DOUT, and GND pins ⁽¹⁾	±15000	V
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 All other pins ⁽¹⁾	±3000	
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

(see Figure 9-1)⁽¹⁾

			MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	V
			V _{CC} = 5 V	4.5	5	5.5	
V _{IH}	Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V _{CC} = 3.3 V	2		5.5	V
			V _{CC} = 5 V	2.4		5.5	
V _{IL}	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON		0		0.8	V
V _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
V _I	Receiver input voltage			−25		25	V
T _A	Operating free-air temperature		TRS3243C	0		70	°C
			TRS3243I	−40		85	

- (1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		{DB} (SSOP)	{PW} (TSSOP)	UNIT
		16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	76.1	70.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	35.8	21.0	°C/W
R _{θJB}	Junction-to-board thermal resistance	37.4	29.2	°C/W
ψ _{JT}	Junction-to-top characterization parameter	7.4	1.3	°C/W
ψ _{JB}	Junction-to-board characterization parameter	37.0	28.8	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report (SPRA953).

6.5 Electrical Characteristics—Power and Status

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾ (see Figure 9-1)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
I _{CC}	Supply current Automatic power down disabled	No load, FORCEOFF and FORCEON at V _{CC} . T _A = 25°C		0.3	1.2	mA
	Supply current Powered off	No load, FORCEOFF at GND. T _A = 25°C		1	10	μA
	Supply current Automatic power down enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded, All DIN are grounded. T _A = 25°C		1	10	
I _I	Input leakage current of FORCEOFF, FORCEON	V _I = V _{CC} or V _I at GND		±0.01	±1	μA
V _{IT+}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
V _{IT-}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
V _T	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
V _{OH}	INVALID high-level output voltage	I _{OH} = -1 mA, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} - 0.6			V
V _{OL}	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCEON = GND, FORCEOFF = V _{CC}			0.4	V

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

6.6 Electrical Characteristics—Driver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾ (see Figure 9-1)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH} High-level output voltage	All DOUT at R _L = 3 kΩ to GND	5	5.4		V
V _{OL} Low-level output voltage	All DOUT at R _L = 3 kΩ to GND	–5	–5.4		V
V _O Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DIN3 = V _{CC} , 3 kΩ to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA	±5			V
I _{IH} High-level input current	V _I = V _{CC}		±0.01	±1	μA
I _{IL} Low-level input current	V _I at GND		±0.01	±1	μA
V _{hys} Input hysteresis				±1	V
I _{OS} Short-circuit output current ⁽³⁾	V _{CC} = 3.6 V, V _O = 0 V		±35	±60	mA
	V _{CC} = 5.5 V, V _O = 0 V				
r _o Output resistance	V _{CC} = 0 V, V ₊ = 0 V, and V _– = 0 V, V _O = ±2 V	300	10M		Ω
I _{off} Output leakage current	FORCEOFF = GND, V _O = ±12 V, V _{CC} = 3 to 3.6 V			±25	μA
	V _O = ±10 V, V _{CC} = 4.5 to 5.5 V			±25	

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

(3) Short-circuit durations must be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

6.7 Electrical Characteristics—Receiver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾ (see Figure 9-1)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = –1 mA	V _{CC} – 0.6	V _{CC} – 0.1		V
V _{OL} Low-level output voltage	I _{OH} = 1.6 mA			0.4	V
V _{IT+} Positive-going input threshold voltage	V _{CC} = 3.3 V		1.6	2.4	V
	V _{CC} = 5 V		1.9	2.4	
V _{IT–} Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
	V _{CC} = 5 V	0.8	1.4		
V _{hys} Input hysteresis (V _{IT+} – V _{IT–})			0.5		V
I _{off} Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	μA
r _I Input resistance	V _I = ±3 V or ±25 V	3	5	7	kΩ

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

6.8 Switching Characteristics—Power and Status

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 7-5](#))

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	UNIT
t_{valid}	Propagation delay time, low- to high-level output	$V_{\text{CC}} = 5 \text{ V}$	1	μs
t_{invalid}	Propagation delay time, high- to low-level output	$V_{\text{CC}} = 5 \text{ V}$	30	μs
t_{en}	Supply enable time	$V_{\text{CC}} = 5 \text{ V}$	100	μs

(1) All typical values are at $V_{\text{CC}} = 3.3 \text{ V}$ or $V_{\text{CC}} = 5 \text{ V}$, and $T_{\text{A}} = 25^{\circ}\text{C}$.

6.9 Switching Characteristics—Driver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾ (see [Figure 9-1](#))
TRS3243C, TRS3243I

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
Maximum data rate		$R_{\text{L}} = 3 \text{ k}\Omega$ One DOUT switching, $C_{\text{L}} = 1000 \text{ pF}$ See Figure 7-1	150	250		kbps
$t_{\text{sk(p)}}$	Pulse skew ⁽³⁾	$R_{\text{L}} = 3 \text{ k}\Omega$ to $7 \text{ k}\Omega$ $C_{\text{L}} = 150 \text{ pF}$ to 2500 pF See Figure 7-3		100		ns
$\text{SR}(\text{tr})$	Slew rate, transition region (see Figure 7-1)	$V_{\text{CC}} = 3.3 \text{ V}$, $R_{\text{L}} = 3 \text{ k}\Omega$ to $7 \text{ k}\Omega$ $C_{\text{L}} = 150 \text{ pF}$ to 1000 pF	6		30	$\text{V}/\mu\text{s}$
		$C_{\text{L}} = 150 \text{ pF}$ to 2500 pF	4		30	

(1) Test conditions are $C1-C4 = 0.1 \mu\text{F}$ at $V_{\text{CC}} = 3.3 \text{ V} \pm 0.3 \text{ V}$; $C1 = 0.047 \mu\text{F}$, $C2-C4 = 0.33 \mu\text{F}$ at $V_{\text{CC}} = 5 \text{ V} \pm 0.5 \text{ V}$.

(2) All typical values are at $V_{\text{CC}} = 3.3 \text{ V}$ or $V_{\text{CC}} = 5 \text{ V}$, and $T_{\text{A}} = 25^{\circ}\text{C}$.

(3) Pulse skew is defined as $|t_{\text{PLH}} - t_{\text{PHL}}|$ of each channel of the same device.

6.10 Switching Characteristics—Receiver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	TYP ⁽²⁾	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	$C_{\text{L}} = 150 \text{ pF}$, See Figure 7-3	150	ns
t_{PHL}	Propagation delay time, high- to low-level output		150	ns
t_{en}	Output enable time	$C_{\text{L}} = 150 \text{ pF}$, $R_{\text{L}} = 3 \text{ k}\Omega$, See Figure 7-4	200	ns
t_{dis}	Output disable time		200	ns
$t_{\text{sk(p)}}$	Pulse skew ⁽³⁾	See Figure 7-3	50	ns

(1) Test conditions are $C1-C4 = 0.1 \mu\text{F}$ at $V_{\text{CC}} = 3.3 \text{ V} \pm 0.3 \text{ V}$; $C1 = 0.047 \mu\text{F}$, $C2-C4 = 0.33 \mu\text{F}$ at $V_{\text{CC}} = 5 \text{ V} \pm 0.5 \text{ V}$.

(2) All typical values are at $V_{\text{CC}} = 3.3 \text{ V}$ or $V_{\text{CC}} = 5 \text{ V}$, and $T_{\text{A}} = 25^{\circ}\text{C}$.

(3) Pulse skew is defined as $|t_{\text{PLH}} - t_{\text{PHL}}|$ of each channel of the same device.

6.11 Typical Characteristics

$V_{CC} = 3.3\text{ V}$

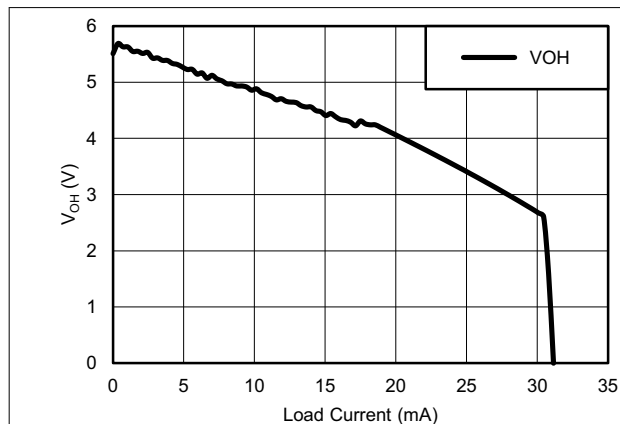


Figure 6-1. DOUT VOH vs Load Current

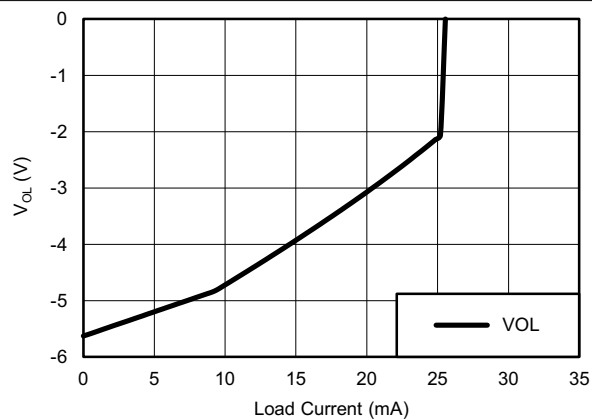
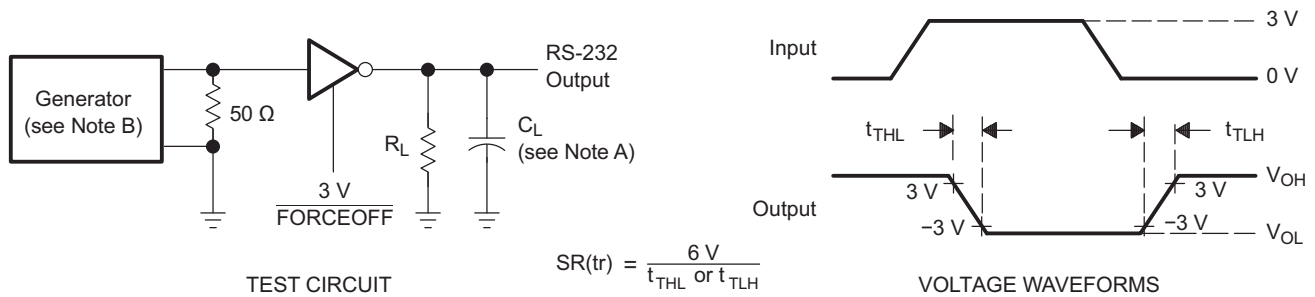


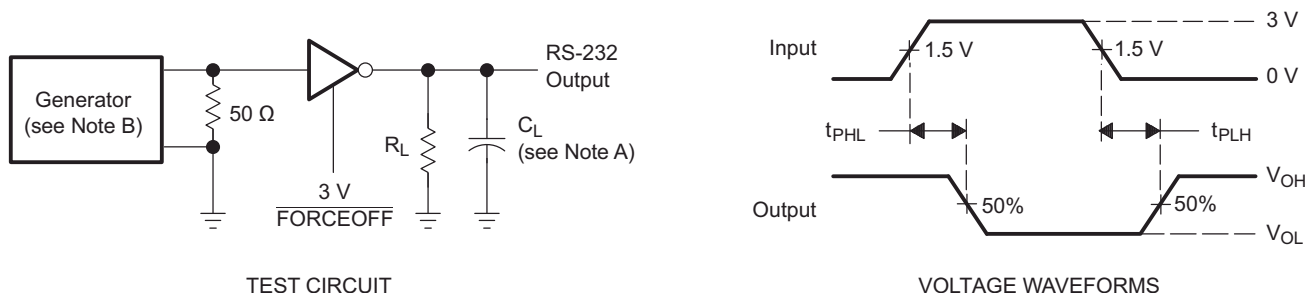
Figure 6-2. DOUT VOL vs Load Current

7 Parameter Measurement Information



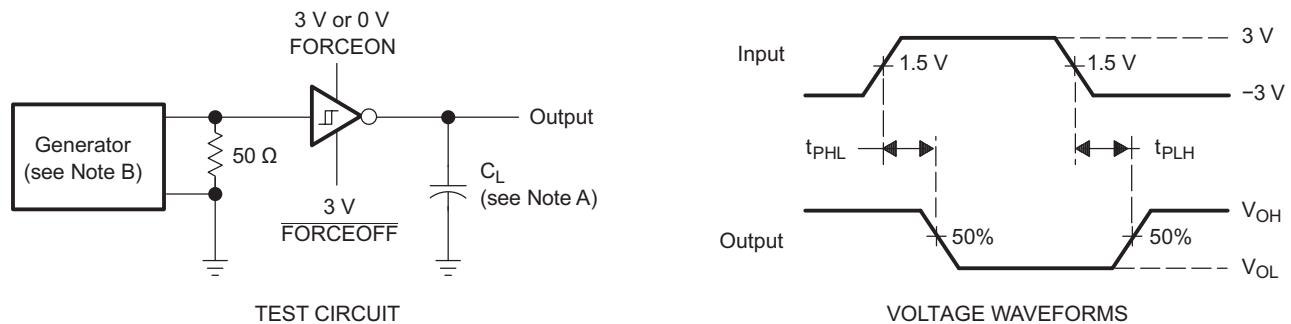
- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbps, (MAX3243C/I) and 1 Mbit/s (MAX3243FC/I), $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 7-1. Driver Slew Rate



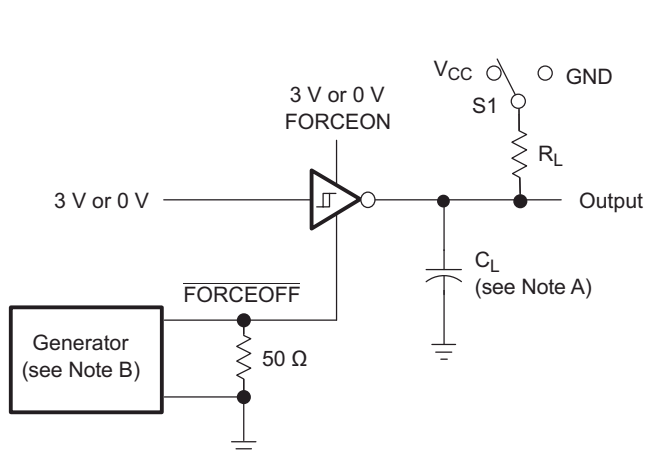
- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbps, (MAX3243C/I) and 1 Mbit/s (MAX3243FC/I), $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 7-2. Driver Pulse Skew

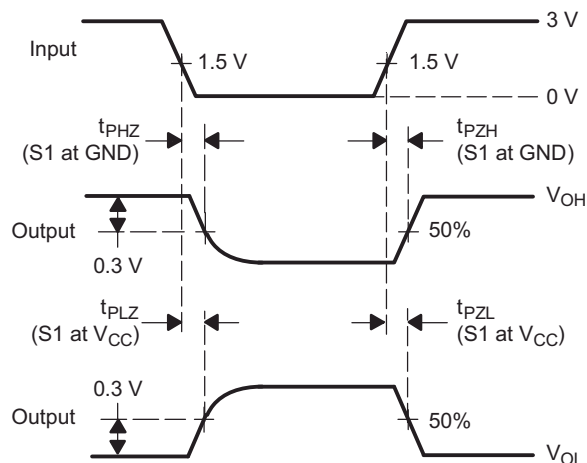


- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 7-3. Receiver Propagation Delay Times



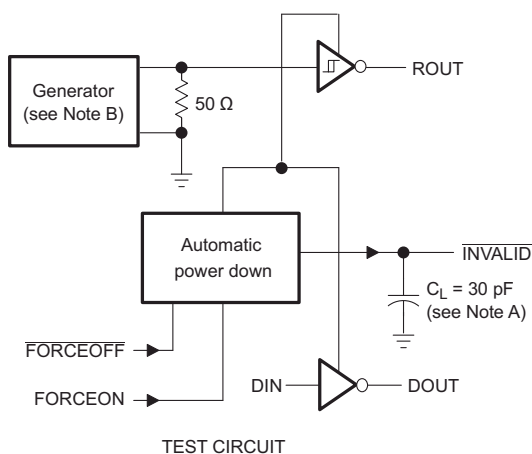
TEST CIRCUIT



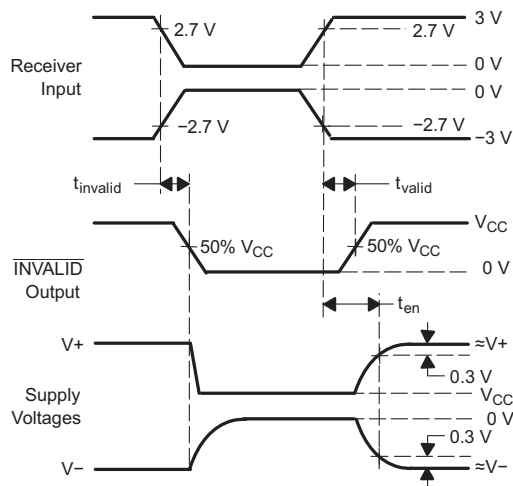
VOLTAGE WAVEFORMS

- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.
- C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- D. t_{PZL} and t_{PZH} are the same as t_{en} .

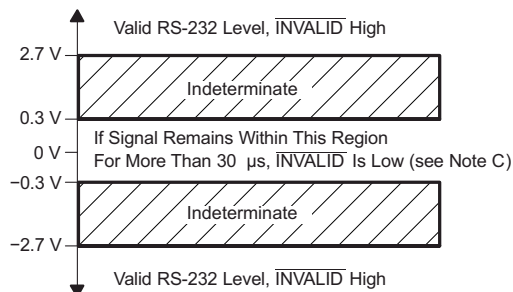
Figure 7-4. Receiver Enable and Disable Times



TEST CIRCUIT



VOLTAGE WAVEFORMS



- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 5 kbps, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.
- C. Automatic power down disables drivers and reduces supply current to $1\ \mu\text{A}$.

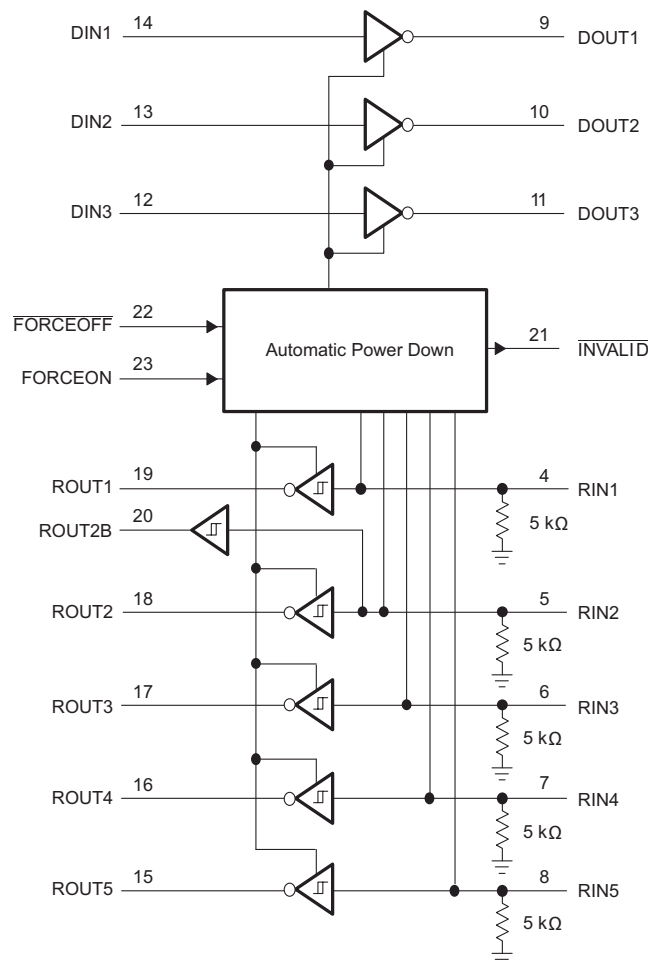
Figure 7-5. $\overline{\text{INVALID}}$ Propagation Delay Times and Supply Enabling Time

8 Detailed Description

8.1 Overview

The TRS3243 device consists of three line drivers, five line receivers, and a dual charge-pump circuit with ± 15 -kV ESD (HBM) protection pin-to-pin (serial-port connection pins, including GND). The TRS3243 device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches what is needed for the typical serial port used in an IBM PC, AT, or compatible device. The charge pump and four small external capacitors allow operation from one 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the device is powered down. Flexible control options for power management are available when the serial port is inactive. The automatic power-down feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 μ A. Disconnecting the serial port or turning off the peripheral drivers causes the automatic power down condition to occur. Automatic power down can be disabled when FORCEON and FORCEOFF are high and must be done when driving a serial mouse. With automatic power down enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V, is less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μ s. INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μ s.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Automatic Power Down

Automatic power down can be used to automatically save power when the receivers are unconnected or when they are connected to a powered down remote RS232 port. FORCEON being high overrides automatic power down and the drivers are active. $\overline{\text{FORCEOFF}}$ being low overrides FORCEON and powers down all outputs except for ROUT2B and $\overline{\text{INVALID}}$.

8.3.2 Charge Pump

The charge pump increases, inverts, and regulates voltage at V+ and V– pins. The charge pump requires four external capacitors.

8.3.3 RS232 Driver

Three drivers interface standard logic level to RS232 levels. All DIN inputs must be valid high or low.

8.3.4 RS232 Receiver

Five receivers interface RS232 levels to standard logic levels. An open input results in a high output on ROUT. Each RIN input includes an internal standard RS232 load.

8.3.5 ROUT2B Receiver

ROUT2B is an always-active, noninverting output of RIN2 input, which allows applications using the ring indicator to transmit data while the device is powered down.

8.3.6 Invalid Input Detection

The $\overline{\text{INVALID}}$ output goes active low when all RIN inputs are unpowered. The $\overline{\text{INVALID}}$ output goes inactive high when any RIN input is connected to an active RS232 voltage level.

8.4 Device Functional Modes

Table 8-1. Each Driver⁽¹⁾

INPUTS				OUTPUT	DRIVER STATUS
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with automatic power down disabled
H	H	H	X	L	
L	L	H	YES	H	Normal operation with automatic power down enabled
H	L	H	YES	L	
X	L	H	NO	Z	Power off by automatic power down feature

(1) H = high level, L = low level, X = irrelevant, Z = high impedance, YES = any RIN valid, NO = all RIN invalid

Table 8-2. Each Receiver⁽¹⁾

INPUTS			OUTPUTS	RECEIVER STATUS
RIN	FORCEON	FORCEOFF	ROUT	
X	X	L	Z	Powered off
L	X	H	H	Normal operation
H	X	H	L	
Open	X	H	H	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

Table 8-3. $\overline{\text{INVALID}}$ and ROUT2B Outputs⁽¹⁾

INPUTS				OUTPUTS		OUTPUT STATUS
VALID RIN RS-232 LEVEL	RIN2	FORCEON	FORCEOFF	$\overline{\text{INVALID}}$	ROUT2B	
YES	L	X	X	H	L	Always Active
YES	H	X	X	H	H	
YES	OPEN	X	X	H	L	Always Active
NO	OPEN	X	X	L	L	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off),
OPEN = input disconnected or connected driver off, YES = any RIN valid, NO = all RIN invalid

9 Application and Implementation

Note

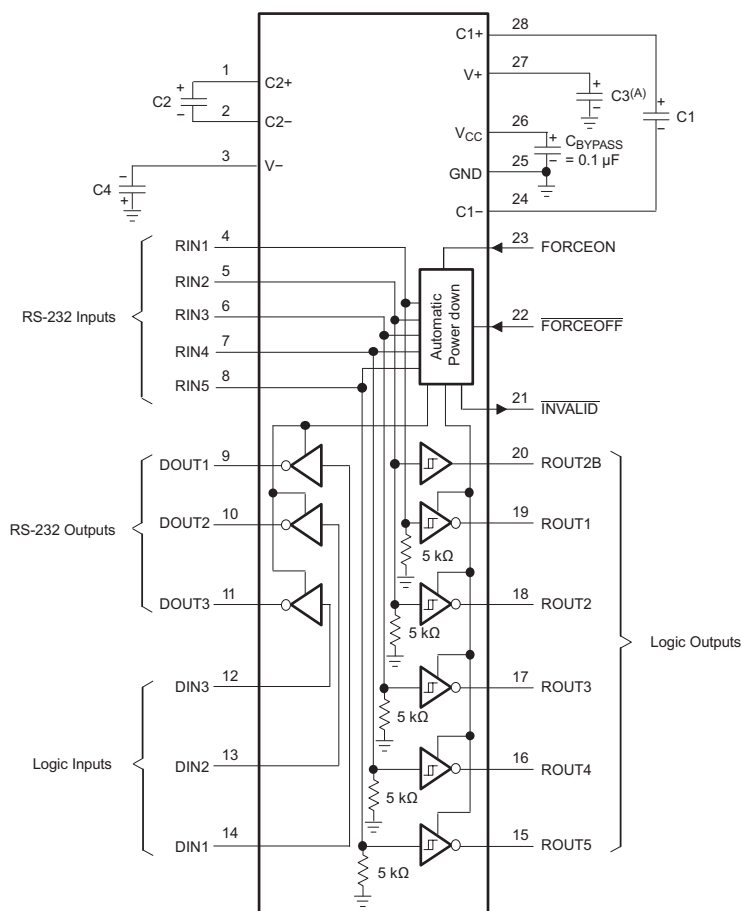
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The TRS3243 device is designed to convert single-ended signals into RS232-compatible signals, and vice-versa.

This device can be used in any application where RS232 line driver or receiver is required. One benefit of this device is its ESD protection, which helps protect other components on the board when the RS232 lines are tied to a physical connector. The device also features an automatic power-down circuit.

9.2 Typical Application



- A. C3 can be connected to V_{CC} or GND.
- B. Resistor values shown are nominal.
- C. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they must be connected as shown.

Figure 9-1. Typical Operating Circuit and Capacitor Values

9.2.1 Design Requirements

- V_{CC} minimum is 3 V and maximum is 5.5 V
- Maximum recommended bit rate is 250 kbps

Table 9-1. V_{CC} versus Capacitor Values

V_{CC}	C1	C2, C3, C4
3.3 V \pm 0.3 V	0.1 μ F	0.1 μ F
5 V \pm 0.5 V	0.047 μ F	0.33 μ F
3 V to 5.5 V	0.1 μ F	0.47 μ F

9.2.2 Detailed Design Procedure

It is recommended to add capacitors as shown in [Figure 9-1](#).

All DIN, $\overline{\text{FORCEOFF}}$ and FORCEON inputs must be connected to valid low or high logic levels.

Select capacitor values based on V_{CC} level for best performance.

9.2.3 Application Curve

V_{CC} = 3.3 V

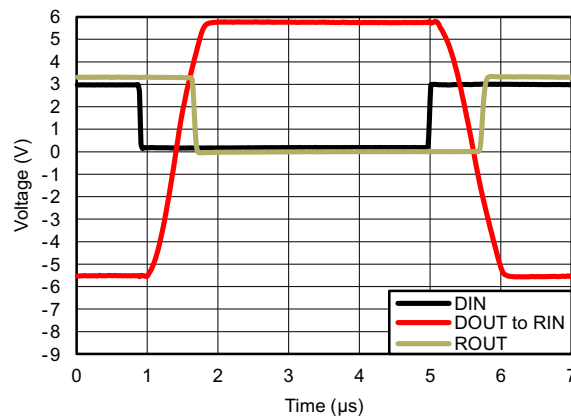


Figure 9-2. Driver to Receiver Loopback Timing Waveform

9.3 Power Supply Recommendations

V_{CC} must be between 3 V and 5.5 V. Charge pump capacitors must be chosen using [Table 9-1](#).

9.4 Layout

9.4.1 Layout Guidelines

Keep the external capacitor traces short. This is more important on C1 and C2 nodes that have the fastest rise and fall times.

[Figure 9-3](#) shows only critical layout sections. Input and output traces will vary in shape and size depending on the customer application. FORCEON and $\overline{\text{FORCEOFF}}$ must be pulled up to V_{CC} or GND through a pullup resistor, depending on which configuration is desired upon powerup.

9.4.2 Layout Example

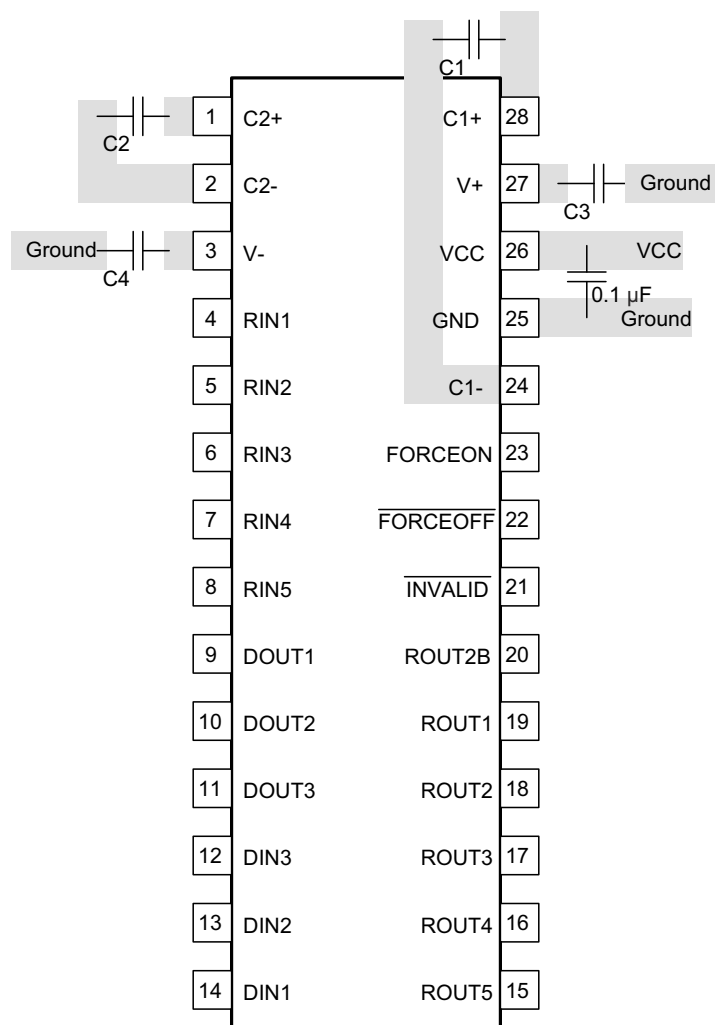


Figure 9-3. Layout Diagram

10 Device and Documentation Support

10.1 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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10.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.4 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TRS3243CDBR	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS3243C
TRS3243IDBR	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS3243I

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

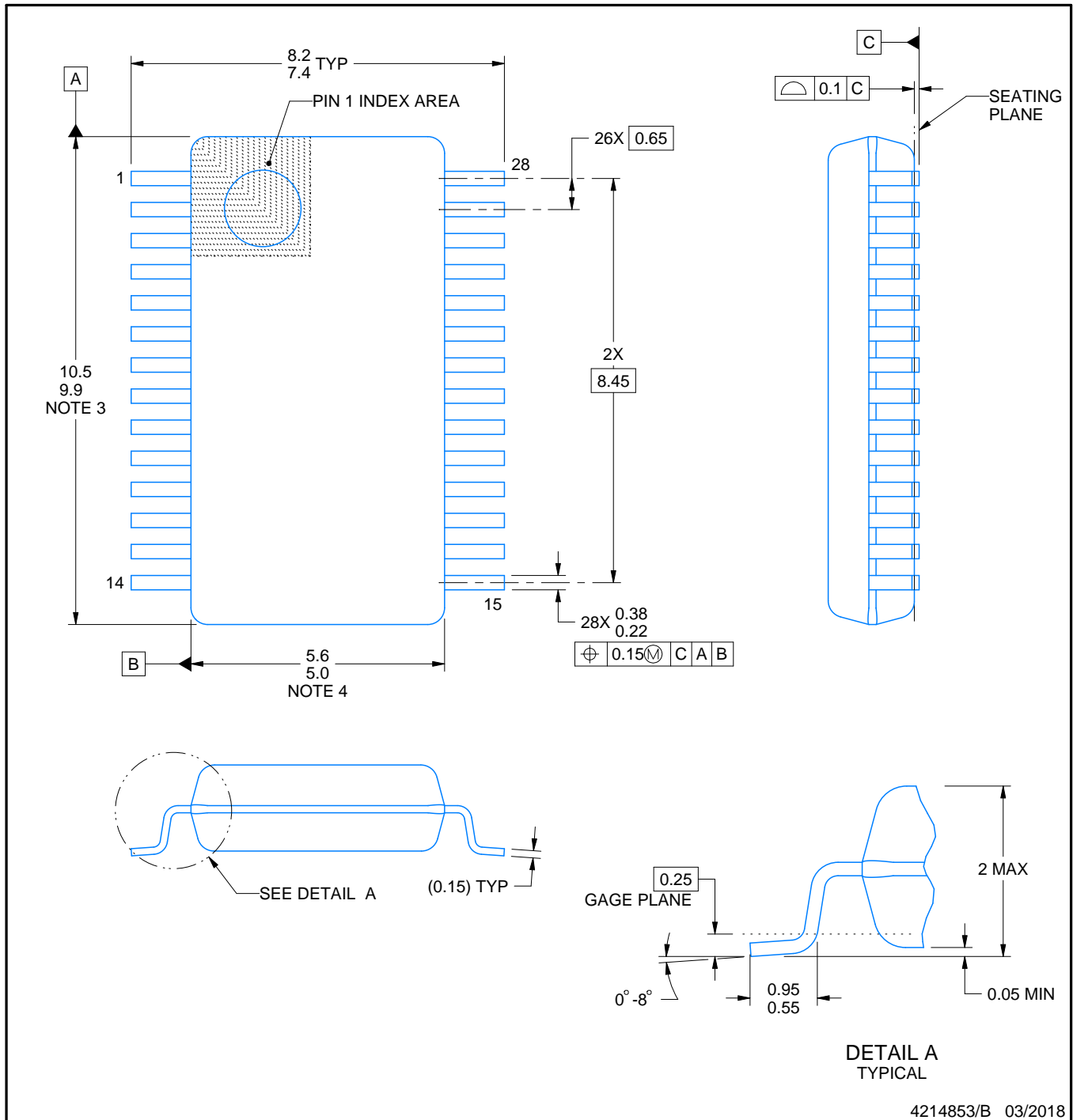
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS3243CDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TRS3243IDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS3243CDBR	SSOP	DB	28	2000	356.0	356.0	35.0
TRS3243IDBR	SSOP	DB	28	2000	356.0	356.0	35.0



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NOTES:

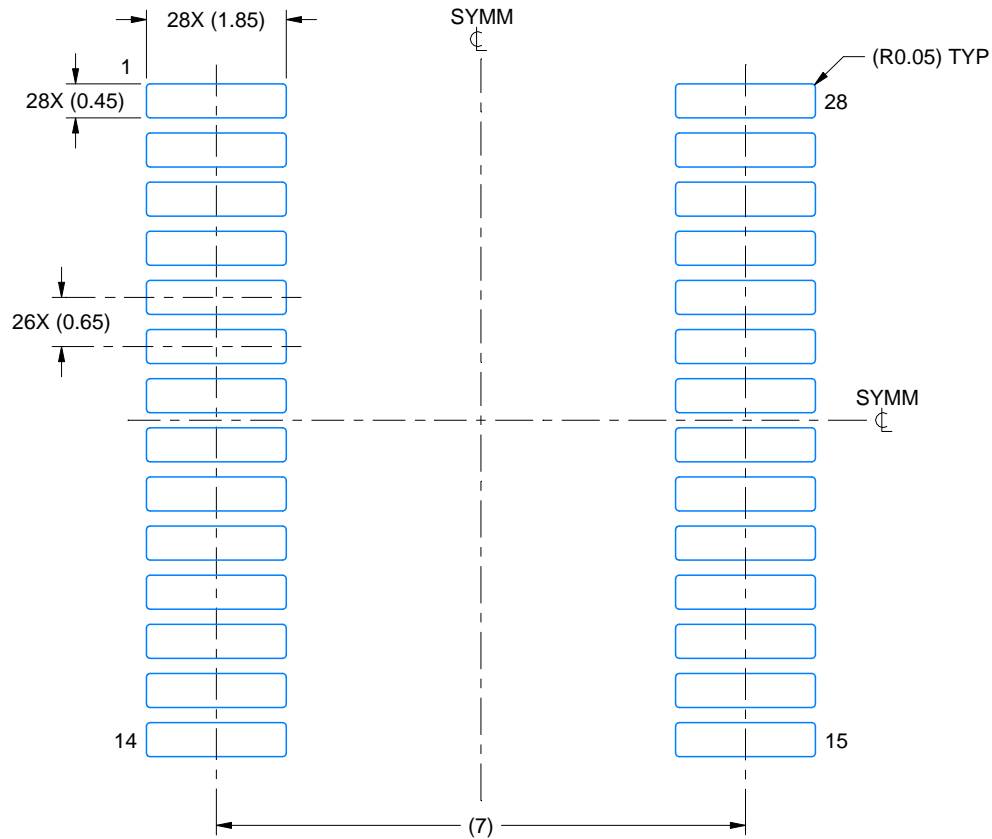
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

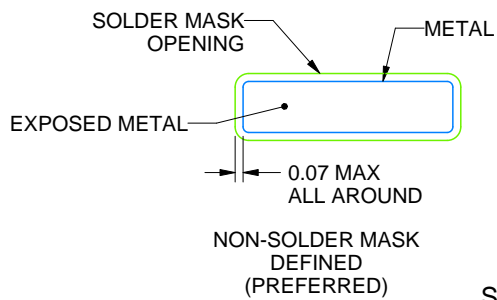
DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

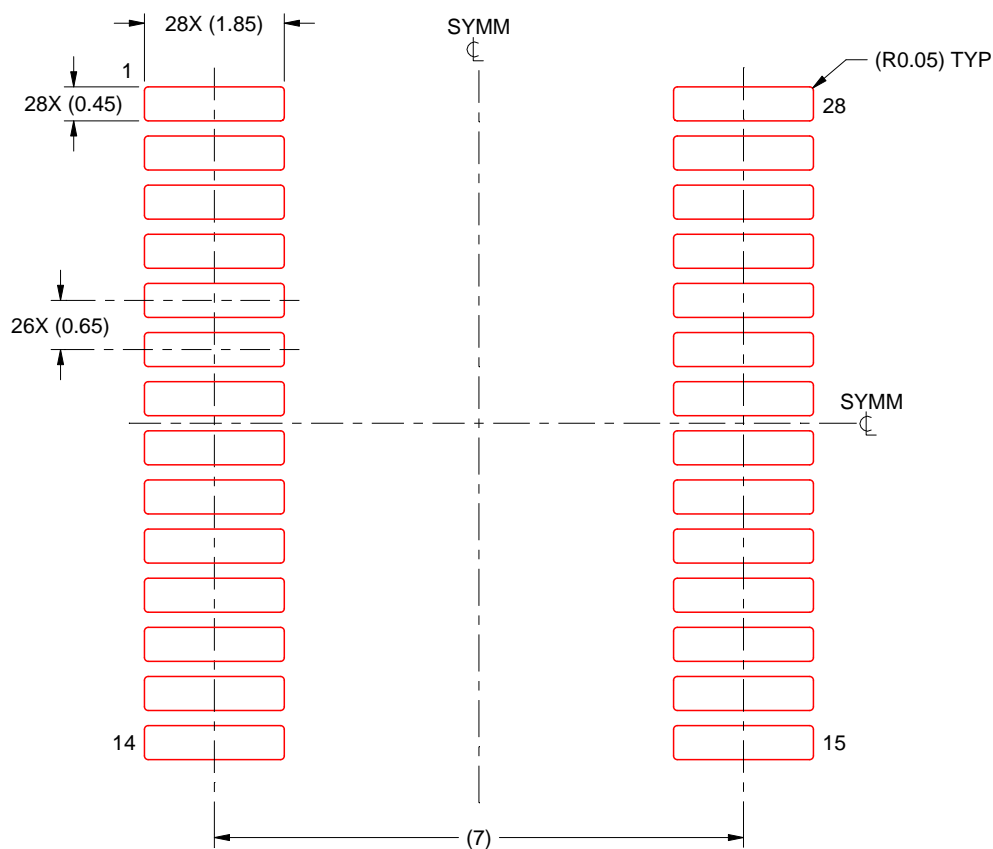
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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